

Amend claim 17 to read as follows:

- --17. A solder useful in kinetically controlled bonding of parts, the solder comprising:
  - a plurality of chemical element layers;
  - at least one of the chemical element layers defining a binary solder, the binary solder having a first melting temperature; and
  - another one of the chemical element layers defining a solder quenching layer;wherein the solder formed by the chemical element layers has a usage temperature which is substantially higher than the first temperature of the binary solder.--

Amend claim 18 to read as follows:

- 18. The solder according to claim 17, wherein the binary solder comprises a sequence of chemical element layers each comprising a single chemical element of the binary solder, the chemical element layers forming a binary mixture close to the eutectic point of the chemical elements at the first melting temperature.--

Amend claim 19 to read as follows:

- 19. The solder according to claim 18, wherein the chemical element layers are gold and tin which form a binary solder mixture close to the eutectic point of gold-tin at the first melting temperature.--